IXYS

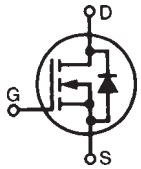
Preliminary Technical Information

TrenchMV™ Power MOSFET

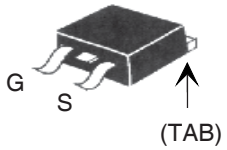
IXTA48N20T
IXTP48N20T

V_{DSS} = 200V
I_{D25} = 48A
$R_{DS(on)}$ ≤ 50mΩ

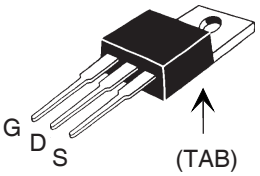
N-Channel Enhancement Mode
Avalanche Rated



TO-263 (IXTA)



TO-220 (IXTP)



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	200	V
V_{DGR}	T_J = 25°C to 175°C, R_{GS} = 1MΩ	200	V
V_{GSM}	Transient	± 30	V
I_{D25}	T_C = 25°C	48	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	130	A
I_{AR}	T_C = 25°C	5	A
E_{AS}	T_C = 25°C	500	mJ
dV/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 175°C$	3	V/ns
P_D	T_C = 25°C	250	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	1.6mm (0.062in.) from case for 10s	300	°C
T_{SOLD}	Plastic body for 10 seconds	260	°C
M_d	Mounting torque (TO-220)	1.13/10	Nm/lb.in
Weight	TO-220	3.0	g
	TO-263	2.5	g

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 250μA	200			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 250μA	2.5		4.5	V
I_{GSS}	V_{GS} = ± 20V, V_{DS} = 0V			± 100	nA
I_{DSS}	$V_{DS} = V_{DSS}$			5	μA
	V_{GS} = 0V T_J = 150°C			250	μA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 24A, Notes 1, 2		40	50	mΩ

Features

- Ultra-low On Resistance
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect
- 175 °C Operating Temperature

Advantages

- Easy to mount
- Space savings
- High power density

Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control
- Uninterruptible power supplies
- High speed power switching applications

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS}= 10V, I_D = 0.5 • I_{D25}, Note 1	26	44		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		3000		pF
C_{oss}			340		pF
C_{rss}			107		pF
$t_{d(on)}$	**Resistive Switching Times**		20		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		26		ns
$t_{d(off)}$	R_G = 15Ω (External)		46		ns
t_f			28		ns
$Q_{g(on)}$	V_{GS}= 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		60		nC
Q_{gs}			18		nC
Q_{gd}			13		nC
R_{thJC}				0.5	°C/W
R_{thCH}	TO-220		0.50		°C/W

Source-Drain Diode

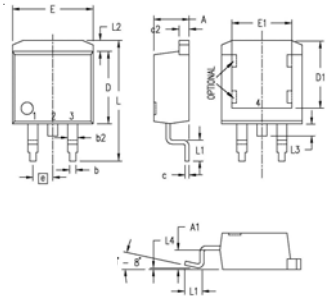
Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			48	A
I_{SM}	Repetitive, pulse width limited by T_{JM}			192	A
V_{SD}	I_F = 24A, V_{GS} = 0V, Note 1			1.2	V
t_{rr}	I_F = 0.5 • I_S, V_{GS} = 0V		130		ns
I_{RM}	-di/dt = 100A/μs		8.5		A
Q_{RM}	V_R = 0.5 • V_{DSS}		0.55		μC

Notes: 1. Pulse test, t ≤ 300μs; duty cycle, d ≤ 2%.
2. On through-hole packages, $R_{DS(on)}$ Kelvin test contact location must be 5mm or less from the package body.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

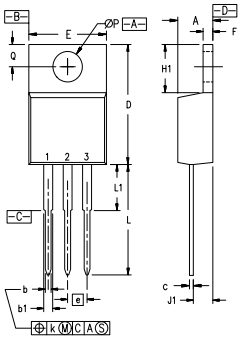
TO-263 (IXTA) Outline



Pins: 1 - Gate 2 - Drain
3 - Source 4, TAB - Drain

Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.06	4.83	.160	.190
A1	2.03	2.79	.080	.110
b	0.51	0.99	.020	.039
b2	1.14	1.40	.045	.055
c	0.46	0.74	.018	.029
c2	1.14	1.40	.045	.055
D	8.64	9.65	.340	.380
D1	7.11	8.13	.280	.320
E	9.65	10.29	.380	.405
E1	6.86	8.13	.270	.320
e	2.54	BSC	.100	BSC
L	14.61	15.88	.575	.625
L1	2.29	2.79	.090	.110
L2	1.02	1.40	.040	.055
L3	1.27	1.78	.050	.070
L4	0	0.38	0	.015
R	0.46	0.74	.018	.029

TO-220 (IXTP) Outline



Pins: 1 - Gate 2 - Drain
3 - Source 4, TAB - Drain

SYM	INCHES MIN	MAX	MILLIMETERS MIN	MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

Fig. 1. Output Characteristics @ 25ºC

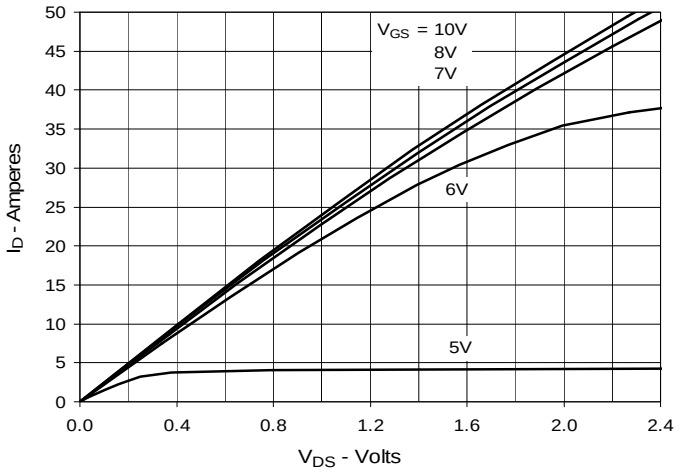


Fig. 2. Extended Output Characteristics @ 25ºC

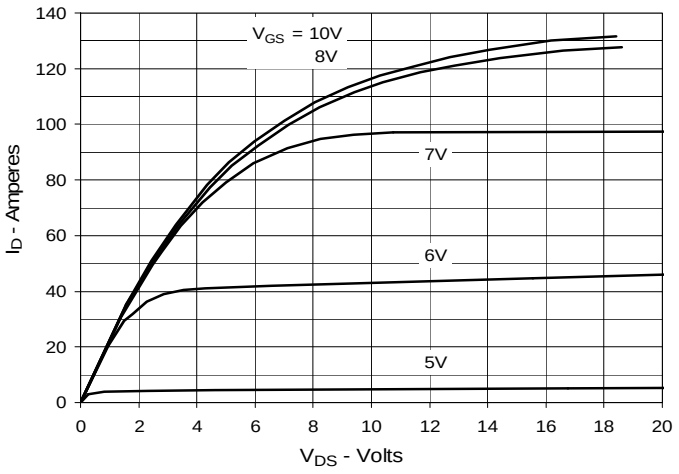


Fig. 3. Output Characteristics @ 150ºC

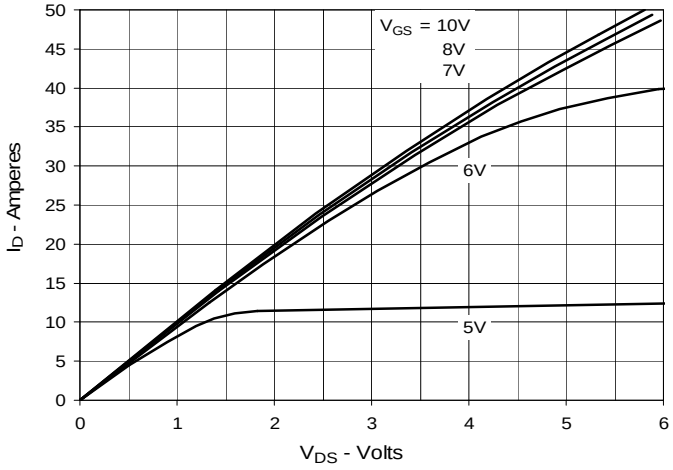


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 24A Value vs. Junction Temperature

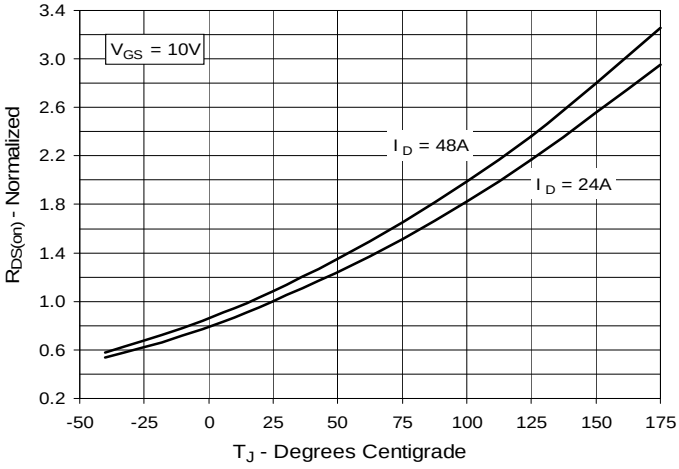


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 24A Value vs. Drain Current

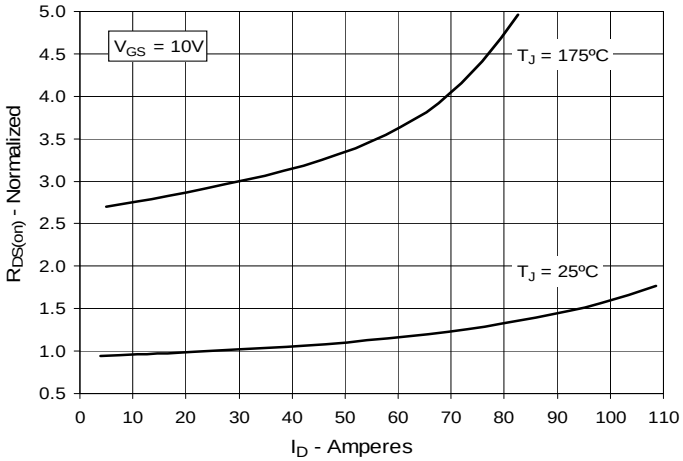


Fig. 6. Maximum Drain Current vs. Case Temperature

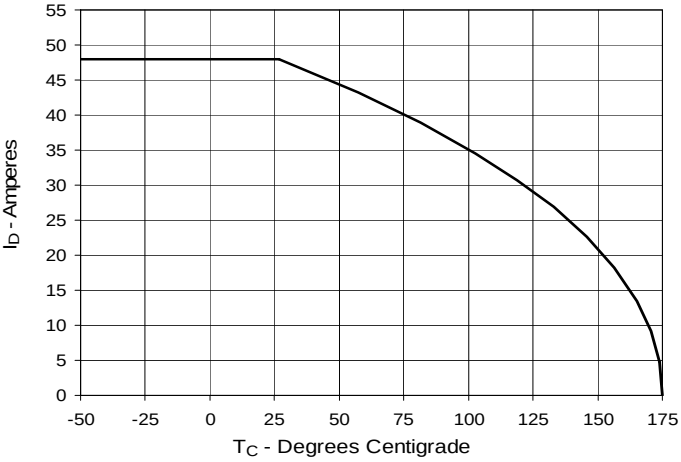


Fig. 7. Input Admittance

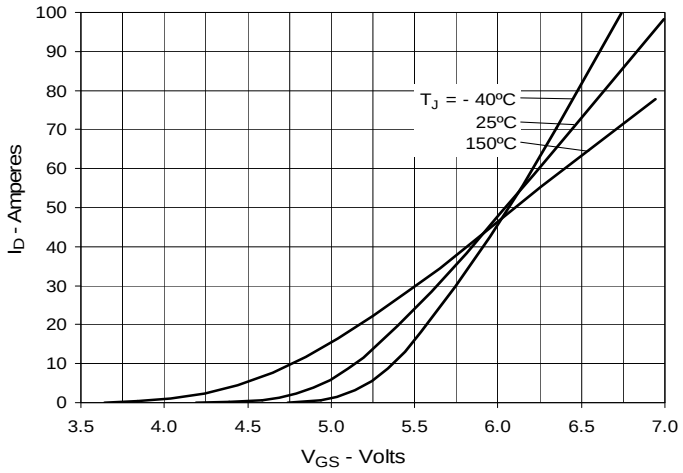


Fig. 8. Transconductance

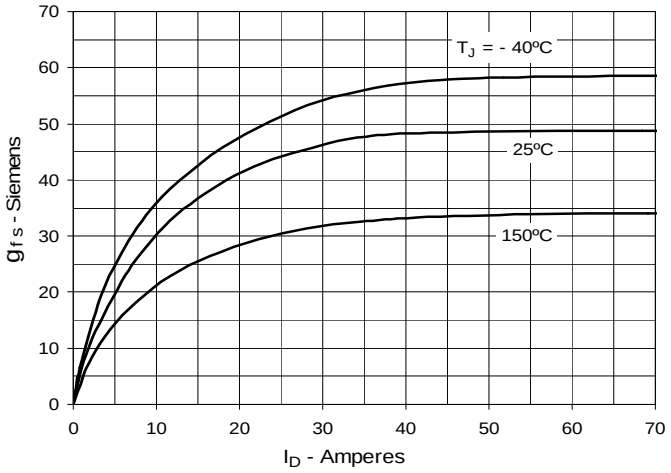


Fig. 9. Forward Voltage Drop of Intrinsic Diode

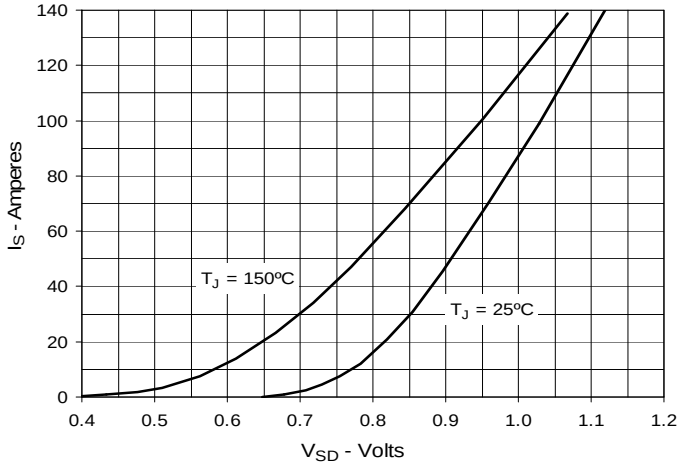


Fig. 10. Gate Charge

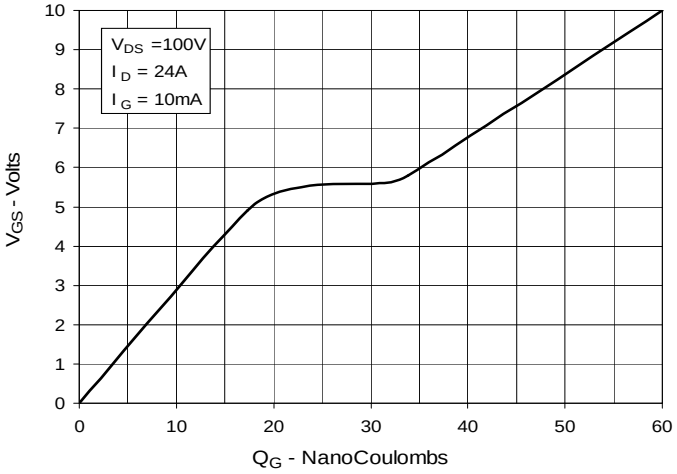


Fig. 11. Capacitance

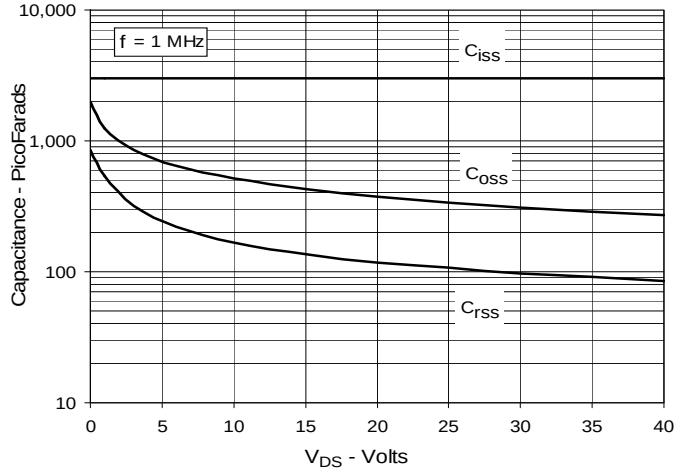


Fig. 12. Maximum Transient Thermal Impedance

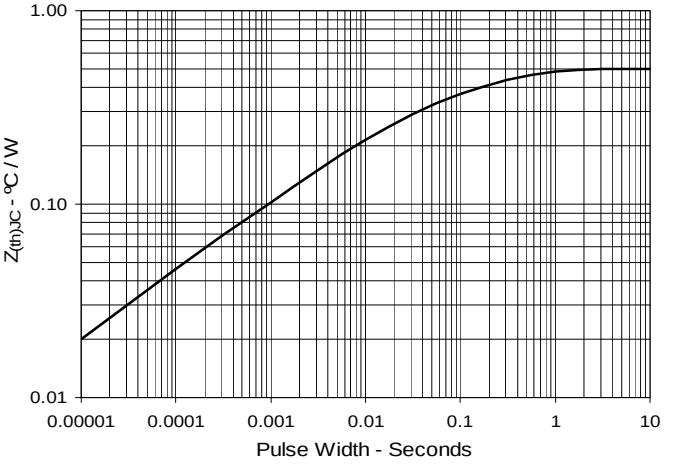


Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

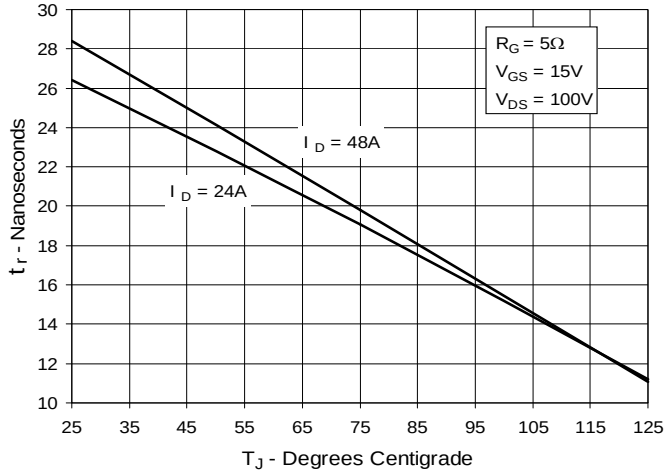


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

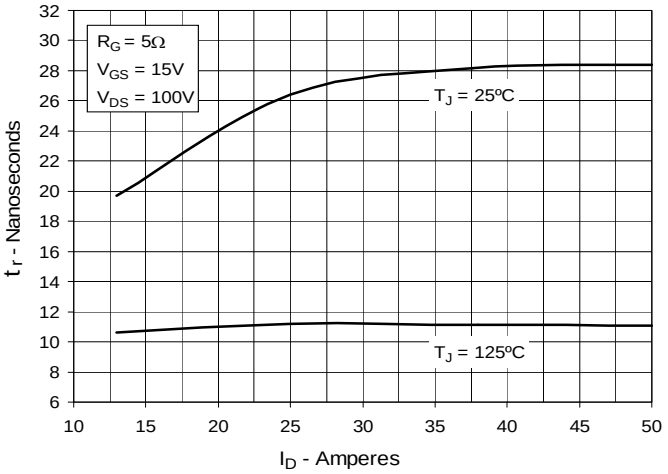


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

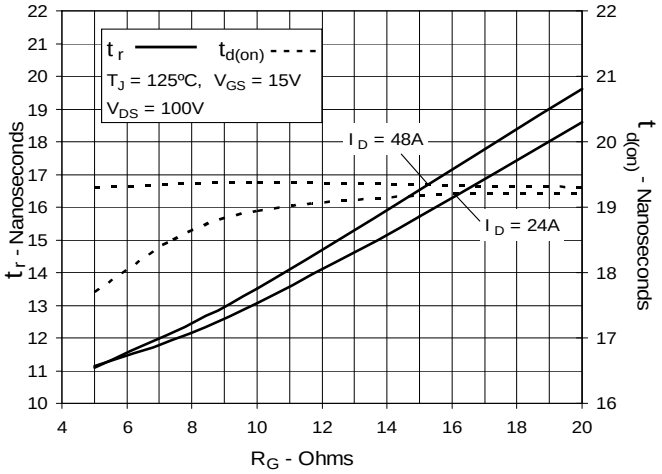


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

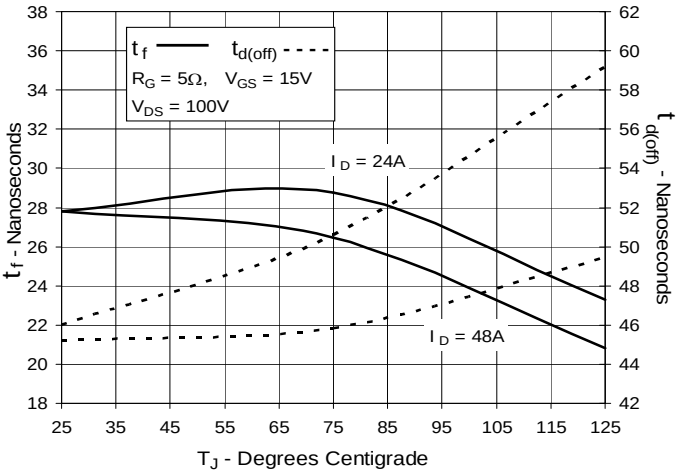


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

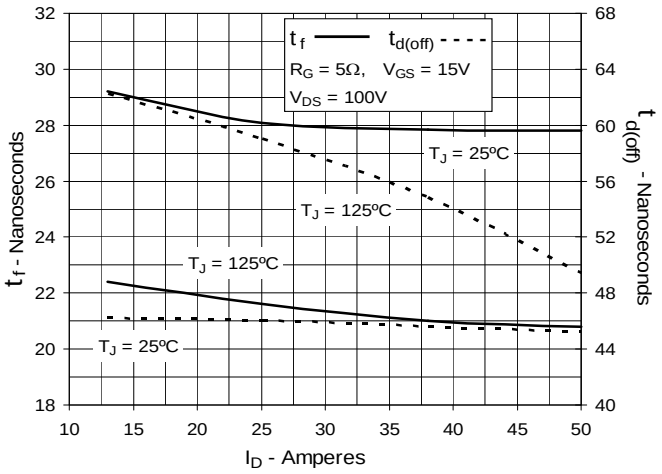


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance